



Attorney Docket No. MTI-31607

#6/A
3-13-03
AJONES

TECHNICAL CENTER 2800
JAN - 9 2003

RECEIVED

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Teck Kheng Lee
Serial No. : 10/050,507
Filing Date : January 16, 2002
For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
Group Art Unit : 2812
Confirmation No. : 7687

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

I hereby certify that, on the date shown below, this correspondence is being:

Mailing
deposited with the United States Postal Service in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

37 CFR 1.8(a) **37 CFR 1.10**
 with sufficient postage as first class mail As "Express Mail Post Office to Addressee" Mailing Label No. EV 264092504 US

Transmission
 transmitted by facsimile to Fax No _____ addressed to Examiner _____ at the US Patent and Trademark Office.

Date: JAN 6, 2003 Send Copy

Assistant Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to substantive examination, Applicant requests the following amendments be made in the application.

IN THE CLAIMS

Please amend the claims as shown in the attached replacement sheets submitted under 37 C.F.R. § 1.121(c). A blacklined version is enclosed to illustrate the amendments to the claims.

01/06/2003 NM0HMM1 00000075 10050507

01 FC:1202
02 FC:1201

558.00 OP
504.00 OP

MKE/814561.1